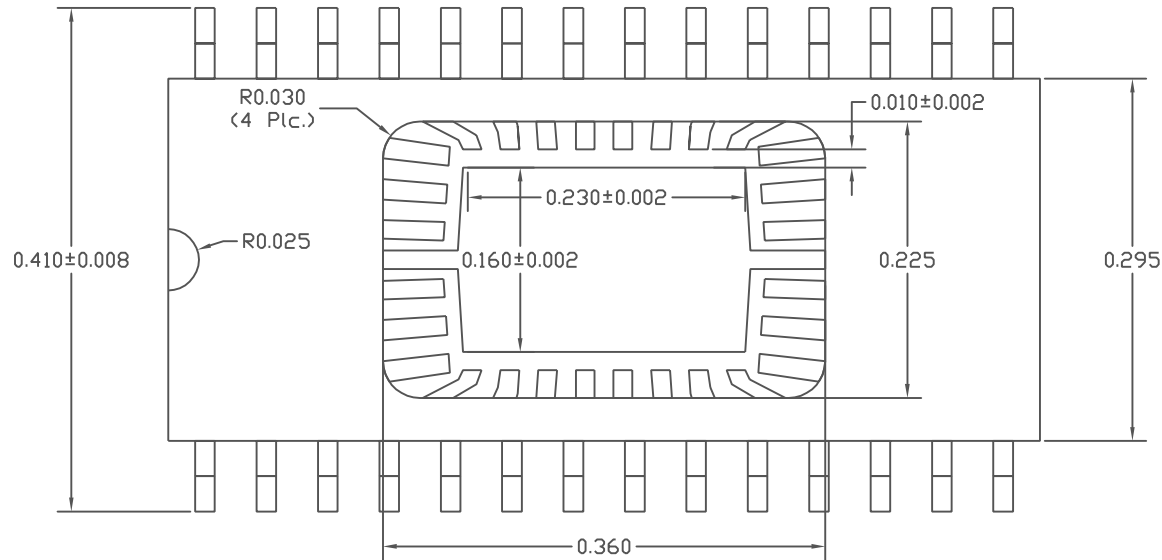
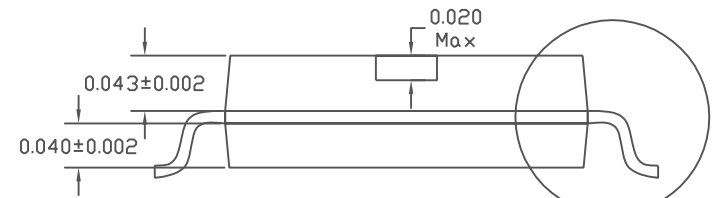
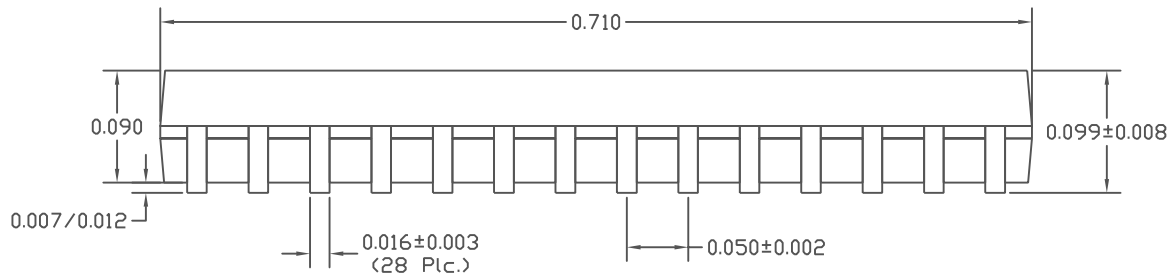
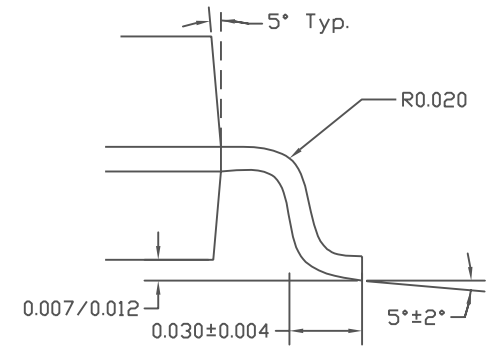


ECN	REV.	DESCRIPTION	DATE:	APP'D:
10022	-	INITIAL RELEASE	02/21/01	BF



DETAIL A-A



NOTES:  
 BODY : Plastic, Semiconductor Grade  
 LEAD FRAME : Copper, Qlin 194  
 LEAD FINISH : 50uIN Au, Over 50uIN Ni  
 FRAME  
 THICKNESS : 0.010" +/-0.001"



TITLE: 28 Lead SOIC Open-Pak

MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.D.
GEN. TOL.: $\pm 0.005$	DATE: 11/12/00	APP'D: BF 2/21/01
SSM P/N: PS0283001	DWG. NO.: SOIC28-OP-01	REV.: -